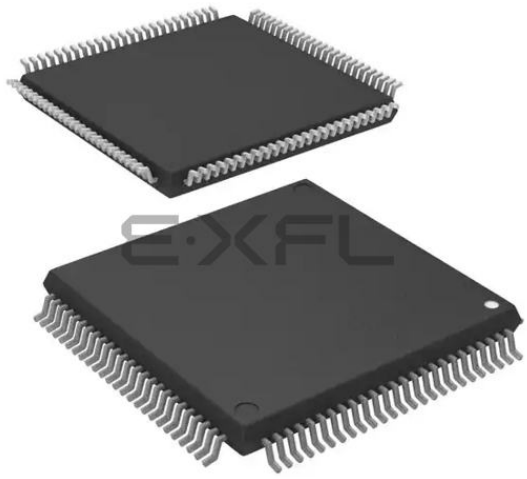
Renesas Electronics America Inc - R5F3650TNFB#30 Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	M16C/60
Core Size	16-Bit
Speed	32MHz
Connectivity	EBI/EMI, I²C, SIO, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	85
Program Memory Size	768KB (768K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	47K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 26x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LFQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f3650tnfb-30

Table 1.6 Product List (2/2) As of July 2012

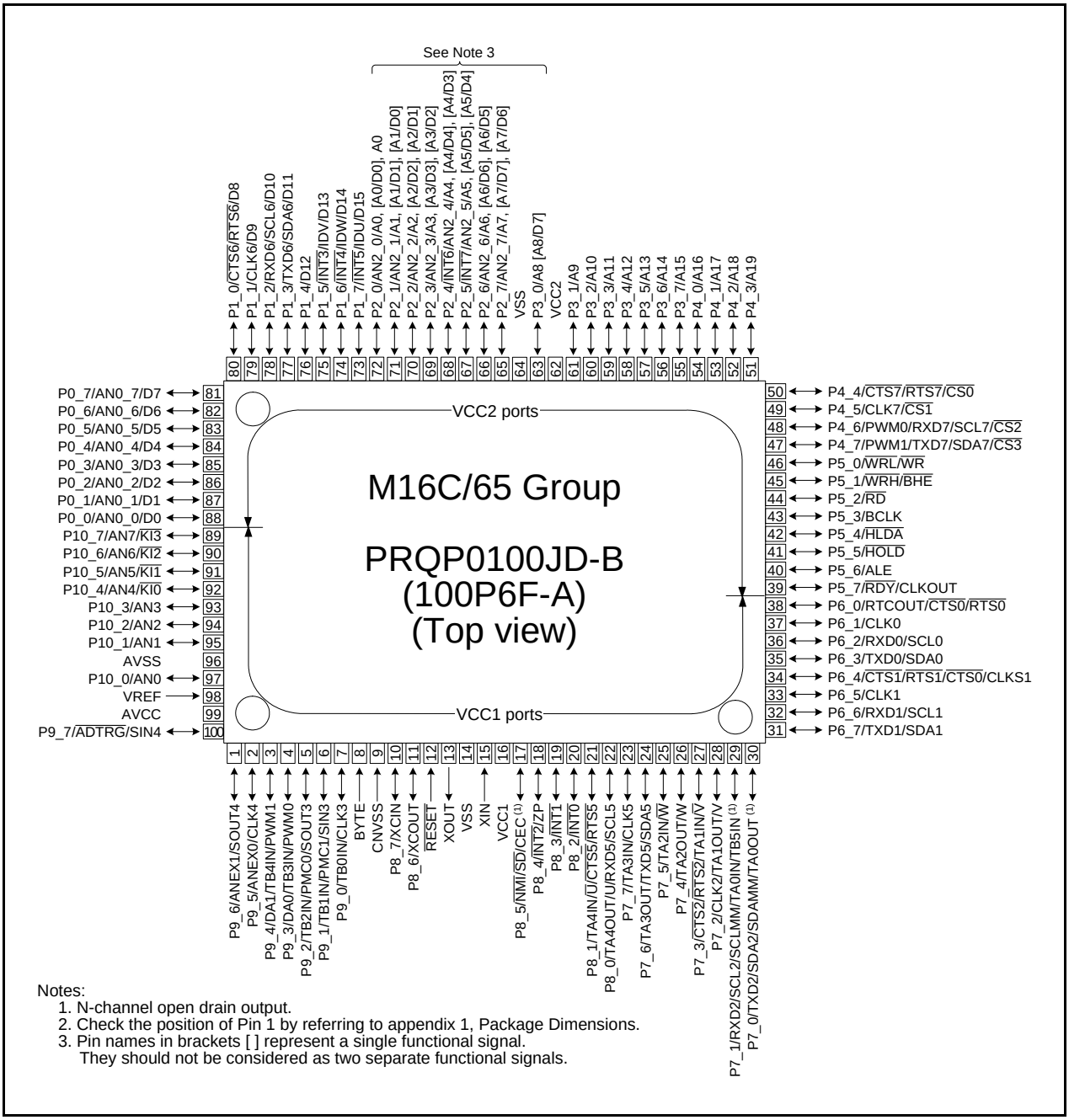
Part No.	ROM Capacity			RAM Capacity	Package Code	Remarks
	Program ROM 1	Program ROM 2	Data flash			
R5F3651TNFC	768 KB	16 KB	4 KB × 2 blocks	47 KB	PLQP0128KB-A	Operating temperature -20°C to 85°C
R5F3650TNFA					PRQP0100JD-B	
R5F3650TNFB					PLQP0100KB-A	
R5F3651TDFC					PLQP0128KB-A	Operating temperature -40°C to 85°C
R5F3650TDFA					PRQP0100JD-B	
R5F3650TDFB					PLQP0100KB-A	

(D): Under development
(P): Planning

Previous package codes are as follows:
PLQP0128KB-A: 128P6Q-A
PRQP0100JD-B: 100P6F-A
PLQP0100KB-A: 100P6Q-A

Table 1.9 Pin Names for the 128-Pin Package (3/3)

Pin No.	Control Pin	Port	I/O Pin for Peripheral Function				Bus Control Pin
			Interrupt	Timer	Serial interface	A/D converter, D/A converter	
101		P1_2			RXD6/SCL6		D10
102		P1_1			CLK6		D9
103		P1_0			$\overline{\text{CTS6/RTS6}}$		D8
104		P0_7				AN0_7	D7
105		P0_6				AN0_6	D6
106		P0_5				AN0_5	D5
107		P0_4				AN0_4	D4
108		P0_3				AN0_3	D3
109		P0_2				AN0_2	D2
110		P0_1				AN0_1	D1
111		P0_0				AN0_0	D0
112		P11_7					
113		P11_6					
114		P11_5					
115		P11_4					
116		P11_3					
117		P11_2					
118		P11_1					
119		P11_0					
120		P10_7	$\overline{\text{KI3}}$			AN7	
121		P10_6	$\overline{\text{KI2}}$			AN6	
122		P10_5	$\overline{\text{KI1}}$			AN5	
123		P10_4	$\overline{\text{KI0}}$			AN4	
124		P10_3				AN3	
125		P10_2				AN2	
126		P10_1				AN1	
127	AVSS						
128		P10_0				AN0	



Notes:
1. N-channel open drain output.
2. Check the position of Pin 1 by referring to appendix 1, Package Dimensions.
3. Pin names in brackets [ ] represent a single functional signal.
They should not be considered as two separate functional signals.

Figure 1.6 Pin Assignment for the 100-Pin Package

Table 1.15 Pin Functions for the 100-Pin Package (1/3)

Signal Name	Pin Name	I/O	Power Supply	Description
Power supply input	VCC1, VCC2, VSS	I	-	Apply 2.7 to 5.5 V to pins VCC1 and VCC2 (VCC1 ≥ VCC2) and 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	I	VCC1	This is the power supply for the A/D and D/A converters. Connect the AVCC pin to VCC1, and connect the AVSS pin to VSS.
Reset input	$\overline{\text{RESET}}$	I	VCC1	Driving this pin low resets the MCU.
CNVSS	CNVSS	I	VCC1	Input pin to switch processor modes. After a reset, to start operating in single-chip mode, connect the CNVSS pin to VSS via a resistor. To start operating in microprocessor mode, connect the pin to VCC1.
External data bus width select input	BYTE	I	VCC1	Input pin to select the data bus of the external area. The data bus is 16 bits when it is low, and 8 bits when it is high. This pin must be fixed either high or low. Connect the BYTE pin to VSS in single-chip mode.
Bus control pins	D0 to D7	I/O	VCC2	Inputs or outputs data (D0 to D7) while accessing an external area with a separate bus.
	D8 to D15	I/O	VCC2	Inputs or outputs data (D8 to D15) while accessing an external area with a 16-bit separate bus.
	A0 to A19	O	VCC2	Outputs address bits A0 to A19.
	A0/D0 to A7/D7	I/O	VCC2	Inputs or outputs data (D0 to D7) and outputs address bits (A0 to A7) by timesharing, while accessing an external area with an 8-bit multiplexed bus.
	A1/D0 to A8/D7	I/O	VCC2	Inputs or outputs data (D0 to D7) and outputs address bits (A1 to A8) by timesharing, while accessing an external area with a 16-bit multiplexed bus.
	$\overline{\text{CS0}}$ to $\overline{\text{CS3}}$	O	VCC2	Outputs chip-select signals $\overline{\text{CS0}}$ to $\overline{\text{CS3}}$ to specify an external area.
	$\overline{\text{WRL}}$/$\overline{\text{WR}}$ $\overline{\text{WRH}}$/$\overline{\text{BHE}}$ $\overline{\text{RD}}$	O	VCC2	Outputs $\overline{\text{WRL}}$, $\overline{\text{WRH}}$, ($\overline{\text{WR}}$, $\overline{\text{BHE}}$), and $\overline{\text{RD}}$ signals. $\overline{\text{WRL}}$ and $\overline{\text{WRH}}$ can be switched with $\overline{\text{BHE}}$ and $\overline{\text{WR}}$. • $\overline{\text{WRL}}$, $\overline{\text{WRH}}$, and $\overline{\text{RD}}$ selected If the external data bus is 16 bits, data is written to an even address in an external area when $\overline{\text{WRL}}$ is driven low. Data is written to an odd address when $\overline{\text{WRH}}$ is driven low. Data is read when $\overline{\text{RD}}$ is driven low. • $\overline{\text{WR}}$, $\overline{\text{BHE}}$, and $\overline{\text{RD}}$ selected Data is written to an external area when $\overline{\text{WR}}$ is driven low. Data in an external area is read when $\overline{\text{RD}}$ is driven low. An odd address is accessed when $\overline{\text{BHE}}$ is driven low. Select $\overline{\text{WR}}$, $\overline{\text{BHE}}$, and $\overline{\text{RD}}$ when using an 8-bit external data bus.
	ALE	O	VCC2	Outputs an ALE signal to latch the address.
	$\overline{\text{HOLD}}$	I	VCC2	$\overline{\text{HOLD}}$ input is unavailable. Connect the $\overline{\text{HOLD}}$ pin to VCC2 via a resistor (pull-up).
	$\overline{\text{HLDA}}$	O	VCC2	In a hold state, $\overline{\text{HLDA}}$ outputs a low-level signal.
	$\overline{\text{RDY}}$	I	VCC2	The MCU bus is placed in a wait state while the $\overline{\text{RDY}}$ pin is driven low.

Power supply: VCC2 is used to supply power to the external bus associated pins. The dual power supply configuration allows VCC2 to interface at a different voltage than VCC1.

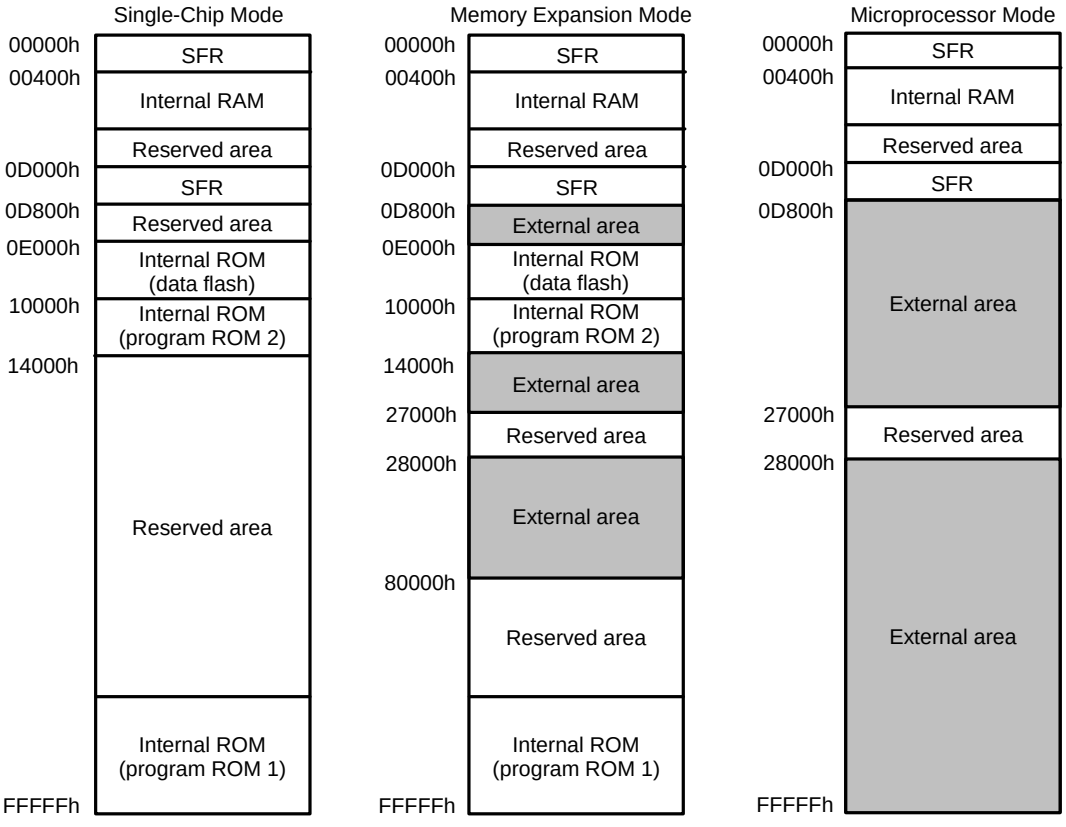
3.3 Accessible Area in Each Mode

Areas that can be accessed vary depending on processor mode and the status of each control bit. Figure 3.3 shows the Accessible Area in Each Mode.

In single-chip mode, the SFRs, internal RAM, and internal ROM can be accessed.

In memory expansion mode, the SFRs, internal RAM, internal ROM, and external areas can be accessed. Address space is expandable to 4 MB with the memory area expansion function.

In microprocessor mode, the SFRs, internal RAM, and external areas can be accessed. Address space is expandable to 4 MB with the memory area expansion function. Allocate ROM to the fixed vector table from FFFDCh to FFFFFh.



Notes:
1. Do not access reserved areas.
2. The figure above applies under the following conditions:
   Single-chip mode and memory expansion mode
   - The PM10 bit in the PM1 register is 1
     (addresses 0E000h to 0FFFFh are used as data flash)
   - The PRG2C0 bit in the PRG2C register is 0 (program ROM 2 enabled)
   - The PM13 bit in the PM1 register is 1
     (all areas in internal RAM, and the program ROM 1 area from 80000h are usable)
   - The IRON bit in the PRG2C register is 1
     (program ROM 1 in addresses 40000h to 7FFFFh enabled)

   Microprocessor mode
   - The PM10 bit is 0 (addresses 0E000h to 0FFFFh are used as the $\overline{CS2}$ area)
   - The PRG2C0 bit is 1 (program ROM 2 disabled)

Figure 3.3 Accessible Area in Each Mode

Table 4.2 SFR Information (2) (1)

Address	Register	Symbol	Reset Value
0020h			
0021h			
0022h	40 MHz On-Chip Oscillator Control Register 0	FRA0	XXXX XX00b
0023h			
0024h			
0025h			
0026h	Voltage Monitor Function Select Register	VWCE	00h
0027h			
0028h	Voltage Detector 1 Level Select Register	VD1LS	0000 1010b(2)
0029h			
002Ah	Voltage Monitor 0 Control Register	VW0C	1000 XX10b (2)
002Bh	Voltage Monitor 1 Control Register	VW1C	1000 1010b (2)
002Ch	Voltage Monitor 2 Control Register	VW2C	1000 0X10b (2)
002Dh			
002Eh			
002Fh			
0030h			
0031h			
0032h			
0033h			
0034h			
0035h			
0036h			
0037h			
0038h			
0039h			
003Ah			
003Bh			
003Ch			
003Dh			
003Eh			
003Fh			

X: Undefined

Notes:
1. The blank areas are reserved. No access is allowed.
2. This is the reset value after hardware reset. Refer to the explanation of each register for details.

Table 4.5 SFR Information (5) (1)

Address	Register	Symbol	Reset Value
0180h	DMA0 Source Pointer	SAR0	XXh
0181h			XXh
0182h			0Xh
0183h			
0184h	DMA0 Destination Pointer	DAR0	XXh
0185h			XXh
0186h			0Xh
0187h			
0188h	DMA0 Transfer Counter	TCR0	XXh
0189h			XXh
018Ah			
018Bh			
018Ch	DMA0 Control Register	DM0CON	0000 0X00b
018Dh			
018Eh			
018Fh			
0190h	DMA1 Source Pointer	SAR1	XXh
0191h			XXh
0192h			0Xh
0193h			
0194h	DMA1 Destination Pointer	DAR1	XXh
0195h			XXh
0196h			0Xh
0197h			
0198h	DMA1 Transfer Counter	TCR1	XXh
0199h			XXh
019Ah			
019Bh			
019Ch	DMA1 Control Register	DM1CON	0000 0X00b
019Dh			
019Eh			
019Fh			
01A0h	DMA2 Source Pointer	SAR2	XXh
01A1h			XXh
01A2h			0Xh
01A3h			
01A4h	DMA2 Destination Pointer	DAR2	XXh
01A5h			XXh
01A6h			0Xh
01A7h			
01A8h	DMA2 Transfer Counter	TCR2	XXh
01A9h			XXh
01AAh			
01ABh			
01ACh	DMA2 Control Register	DM2CON	0000 0X00b
01ADh			
01AEh			
01AFh			

X: Undefined

Note:
1. The blank areas are reserved. No access is allowed.

Table 4.16 SFR Information (16) (1)

Address	Register	Symbol	Reset Value
03C0h	A/D Register 0	AD0	XXXX XXXXb
03C1h			0000 00XXb
03C2h	A/D Register 1	AD1	XXXX XXXXb
03C3h			0000 00XXb
03C4h	A/D Register 2	AD2	XXXX XXXXb
03C5h			0000 00XXb
03C6h	A/D Register 3	AD3	XXXX XXXXb
03C7h			0000 00XXb
03C8h	A/D Register 4	AD4	XXXX XXXXb
03C9h			0000 00XXb
03CAh	A/D Register 5	AD5	XXXX XXXXb
03CBh			0000 00XXb
03CCh	A/D Register 6	AD6	XXXX XXXXb
03CDh			0000 00XXb
03CEh	A/D Register 7	AD7	XXXX XXXXb
03CFh			0000 00XXb
03D0h			
03D1h			
03D2h			
03D3h			
03D4h	A/D Control Register 2	ADCON2	0000 X00Xb
03D5h			
03D6h	A/D Control Register 0	ADCON0	0000 0XXXb
03D7h	A/D Control Register 1	ADCON1	0000 X000b
03D8h	D/A0 Register	DA0	00h
03D9h			
03DAh	D/A1 Register	DA1	00h
03DBh			
03DCh	D/A Control Register	DACON	00h
03DDh			
03DEh			
03DFh			
03E0h	Port P0 Register	P0	XXh
03E1h	Port P1 Register	P1	XXh
03E2h	Port P0 Direction Register	PD0	00h
03E3h	Port P1 Direction Register	PD1	00h
03E4h	Port P2 Register	P2	XXh
03E5h	Port P3 Register	P3	XXh
03E6h	Port P2 Direction Register	PD2	00h
03E7h	Port P3 Direction Register	PD3	00h
03E8h	Port P4 Register	P4	XXh
03E9h	Port P5 Register	P5	XXh
03EAh	Port P4 Direction Register	PD4	00h
03EBh	Port P5 Direction Register	PD5	00h
03ECh	Port P6 Register	P6	XXh
03EDh	Port P7 Register	P7	XXh
03EEh	Port P6 Direction Register	PD6	00h
03EFh	Port P7 Direction Register	PD7	00h

X: Undefined

Note:
1. The blank areas are reserved. No access is allowed.

4.2 Notes on SFRs

4.2.1 Register Settings

Table 4.19 lists Registers with Write-Only Bits and registers whose function differs between reading and writing. Set these registers with immediate values. Do not use read-modify-write instructions. When establishing the next value by altering the existing value, write the existing value to the RAM as well as to the register. Transfer the next value to the register after making changes in the RAM.
Read-modify-write instructions can be used when writing to the no register bits.

Table 4.19 Registers with Write-Only Bits

Address	Register	Symbol
0249h	UART0 Bit Rate Register	U0BRG
024Bh to 024Ah	UART0 Transmit Buffer Register	U0TB
0259h	UART1 Bit Rate Register	U1BRG
025Bh to 025Ah	UART1 Transmit Buffer Register	U1TB
0269h	UART2 Bit Rate Register	U2BRG
026Bh to 026Ah	UART2 Transmit Buffer Register	U2TB
0273h	SI/O3 Bit Rate Register	S3BRG
0277h	SI/O4 Bit Rate Register	S4BRG
0289h	UART5 Bit Rate Register	U5BRG
028Bh to 028Ah	UART5 Transmit Buffer Register	U5TB
0299h	UART6 Bit Rate Register	U6BRG
029Bh to 029Ah	UART6 Transmit Buffer Register	U6TB
02A9h	UART7 Bit Rate Register	U7BRG
02ABh to 02AAh	UART7 Transmit Buffer Register	U7TB
02B6h	I2C0 Control Register 1	S3D0
02B8h	I2C0 Status Register 0	S10
0303h to 0302h	Timer A1-1 Register	TA11
0305h to 0304h	Timer A2-1 Register	TA21
0307h to 0306h	Timer A4-1 Register	TA41
030Ah	Three-Phase Output Buffer Register 0	IDB0
030Bh	Three-Phase Output Buffer Register 1	IDB1
030Ch	Dead Time Timer	DTT
030Dh	Timer B2 Interrupt Generation Frequency Set Counter	ICTB2
0327h to 0326h	Timer A0 Register	TA0
0329h to 0328h	Timer A1 Register	TA1
032Bh to 032Ah	Timer A2 Register	TA2
032Dh to 032Ch	Timer A3 Register	TA3
032Fh to 032Eh	Timer A4 Register	TA4
037Dh	Watchdog Timer Refresh Register	WDTR
037Eh	Watchdog Timer Start Register	WDTS

5. Electrical Characteristics

5.1 Electrical Characteristics (Common to 3 V and 5 V)

5.1.1 Absolute Maximum Rating

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter		Condition	Rated Value	Unit
V_{CC1}	Supply voltage		$V_{CC1} = AV_{CC}$	–0.3 to 6.5	V
V_{CC2}	Supply voltage		$V_{CC1} = AV_{CC}$	–0.3 to V_{CC1} + 0.1 (1)	V
AV_{CC}	Analog supply voltage		$V_{CC1} = AV_{CC}$	–0.3 to 6.5	V
V_{REF}	Analog reference voltage		$V_{CC1} = AV_{CC}$	–0.3 to V_{CC1} + 0.1 (1)	V
V_I	Input voltage	$\overline{RESET}$, CNVSS, BYTE, P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P14_0, P14_1 XIN		–0.3 to V_{CC1} + 0.3 (1)	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P12_0 to P12_7, P13_0 to P13_7		–0.3 to V_{CC2} + 0.3 (1)	V
		P7_0, P7_1, P8_5		–0.3 to 6.5	V
V_O	Output voltage	P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P14_0, P14_1 XOUT		–0.3 to V_{CC1} + 0.3 (1)	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P12_0 to P12_7, P13_0 to P13_7		–0.3 to V_{CC2} + 0.3 (1)	V
		P7_0, P7_1, P8_5		–0.3 to 6.5	V
P_d	Power consumption		$-40°C < T_{opr} \leq 85°C$	300	mW
T_{opr}	Operating temperature	When the MCU is operating		–20 to 85/–40 to 85	°C
		Flash program erase	Program area	0 to 60	
			Data area	–20 to 85/–40 to 85	
T_{stg}	Storage temperature			–65 to 150	°C

Note:
1. Maximum value is 6.5 V.

Table 5.3 Recommended Operating Conditions (2/3)

V_{CC1} = V_{CC2} = 2.7 to 5.5 V at T_{opr} = -20°C to 85°C/-40°C to 85°C unless otherwise specified.

Symbol	Parameter		Standard			Unit
			Min.	Typ.	Max.	
$I_{OL(sum)}$	Low peak output current	Sum of $I_{OL(peak)}$ at P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P14_0 to P14_1			80.0	mA
		Sum of $I_{OL(peak)}$ at P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_5, P12_0 to P12_7, P13_0 to P13_7			80.0	mA
$I_{OL(peak)}$	Low peak output current	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1			10.0	mA
$I_{OL(avg)}$	Low average output current (1)	P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P12_0 to P12_7, P13_0 to P13_7, P14_0, P14_1			5.0	mA
$f_{(XIN)}$	Main clock input oscillation frequency	V_{CC1} = 2.7 V to 5.5 V	2		20	MHz
$f_{(XCIN)}$	Sub clock oscillation frequency			32.768	50	kHz
$f_{(PLL)}$	PLL clock oscillation frequency	V_{CC1} = 2.7 V to 5.5 V	10		32	MHz
$f_{(BCLK)}$	CPU operation clock		2		32	MHz
$t_{SU(PLL)}$	PLL frequency synthesizer stabilization wait time	V_{CC1} = 5.0 V			2	ms
		V_{CC1} = 3.0 V			3	ms

Note:
1. The average output current is the mean value within 100 ms.

5.2 Electrical Characteristics (V_{CC1} = V_{CC2} = 5 V)

5.2.1 Electrical Characteristics

V_{CC1} = V_{CC2} = 5 V

Table 5.19 Electrical Characteristics (1) [1]

V_{CC1} = V_{CC2} = 4.2 to 5.5 V, V_{SS} = 0 V at T_{opr} = –20°C to 85°C/–40°C to 85°C, $f_{(BCLK)}$ = 32 MHz unless otherwise specified.

Symbol	Parameter			Measuring Condition	Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	High output voltage	P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P14_0, P14_1		I_{OH} = –5 mA	V_{CC1} – 2.0		V_{CC1}	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P12_0 to P12_7, P13_0 to P13_7		I_{OH} = –5 mA	V_{CC2} – 2.0		V_{CC2}	
V_{OH}	High output voltage	P6_0 to P6_7, P7_2 to P7_7, P8_0 to P8_4, P8_6, P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P14_0, P14_1		I_{OH} = –200 µA	V_{CC1} – 0.3		V_{CC1}	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P12_0 to P12_7, P13_0 to P13_7		I_{OH} = –200 µA	V_{CC2} – 0.3		V_{CC2}	
V_{OH}	High output voltage	XOUT	HIGH POWER	I_{OH} = –1 mA	V_{CC1} – 2.0		V_{CC1}	V
			LOW POWER	I_{OH} = –0.5 mA	V_{CC1} – 2.0		V_{CC1}	
	High output voltage	XCOUT	HIGH POWER	With no load applied		2.6		V
			LOW POWER	With no load applied		2.2		
V_{OL}	Low output voltage	P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P14_0, P14_1		I_{OL} = 5 mA			2.0	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P12_0 to P12_7, P13_0 to P13_7		I_{OL} = 5 mA			2.0	
V_{OL}	Low output voltage	P6_0 to P6_7, P7_0 to P7_7, P8_0 to P8_7, P9_0 to P9_7, P10_0 to P10_7, P11_0 to P11_7, P14_0, P14_1		I_{OL} = 200 µA			0.45	V
		P0_0 to P0_7, P1_0 to P1_7, P2_0 to P2_7, P3_0 to P3_7, P4_0 to P4_7, P5_0 to P5_7, P12_0 to P12_7, P13_0 to P13_7		I_{OL} = 200 µA			0.45	
V_{OL}	Low output voltage	XOUT	HIGH POWER	I_{OL} = 1 mA			2.0	V
			LOW POWER	I_{OL} = 0.5 mA			2.0	
	Low output voltage	XCOUT	HIGH POWER	With no load applied		0		V
			LOW POWER	With no load applied		0		

Note:
1. When $V_{CC1} \neq V_{CC2}$, refer to 5 V or 3 V standard depending on the voltage.

$V_{CC1} = V_{CC2} = 5\ V$

5.2.2 Timing Requirements (Peripheral Functions and Others)

($V_{CC1} = V_{CC2} = 5$ V, $V_{SS} = 0$ V, at $T_{opr} = -20°C$ to 85°C/-40°C to 85°C unless otherwise specified)

5.2.2.1 Reset Input ($\overline{\text{RESET}}$ Input)

Table 5.24 Reset Input ($\overline{\text{RESET}}$ Input)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(RSTL)}$	$\overline{\text{RESET}}$ input low pulse width	10		µs

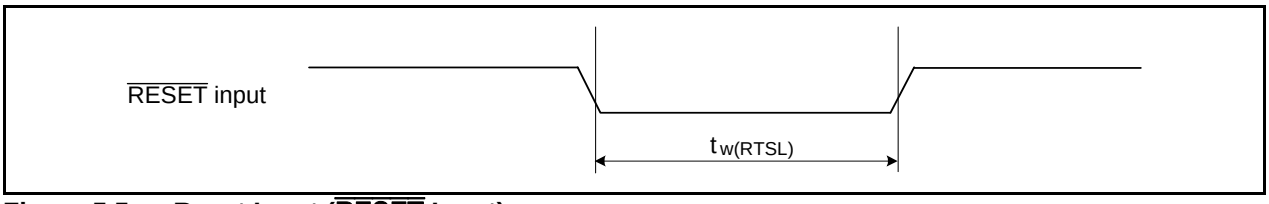


Figure 5.5 Reset Input ($\overline{\text{RESET}}$ Input)

5.2.2.2 External Clock Input

Table 5.25 External Clock Input (XIN Input) (1)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
t_c	External clock input cycle time	50		ns
$t_{w(H)}$	External clock input high pulse width	20		ns
$t_{w(L)}$	External clock input low pulse width	20		ns
t_r	External clock rise time		9	ns
t_f	External clock fall time		9	ns

Note:
1. The condition is $V_{CC1} = V_{CC2} = 3.0$ to 5.0 V.

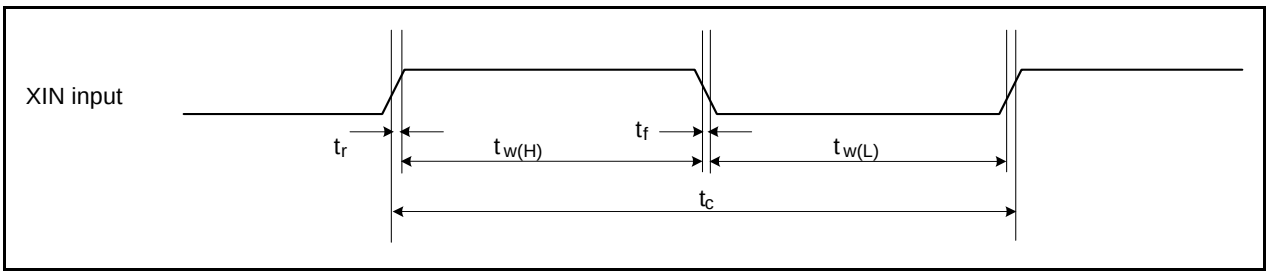


Figure 5.6 External Clock Input (XIN Input)

$V_{CC1} = V_{CC2} = 5\ V$

Timing Requirements

($V_{CC1} = V_{CC2} = 5$ V, $V_{SS} = 0$ V, at T_{opr} = -20°C to 85°C/-40°C to 85°C unless otherwise specified)

Table 5.30 Timer A Input (Two-Phase Pulse Input in Event Counter Mode)

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TA)}$	TAiIN input cycle time	800		ns
$t_{su(TAIN-TAOUT)}$	TAiOUT input setup time	200		ns
$t_{su(TAOUT-TAIN)}$	TAiIN input setup time	200		ns

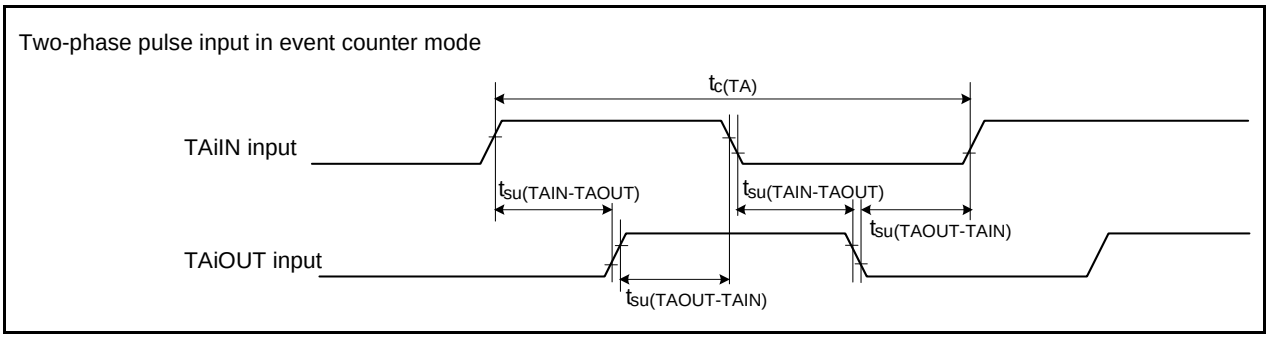
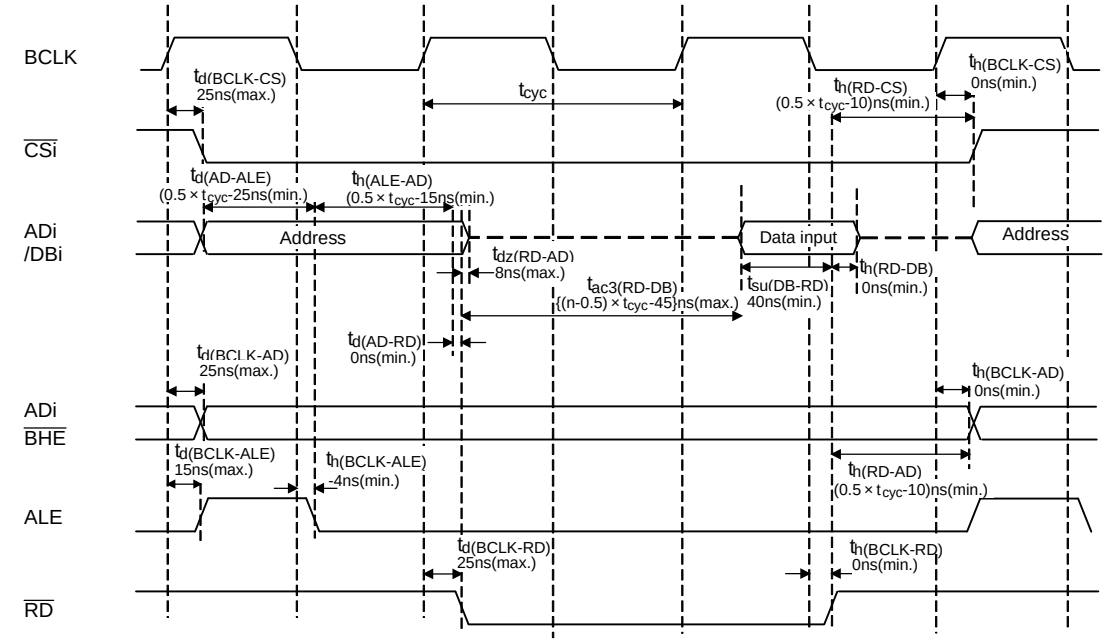


Figure 5.8 Timer A Input (Two-Phase Pulse Input in Event Counter Mode)

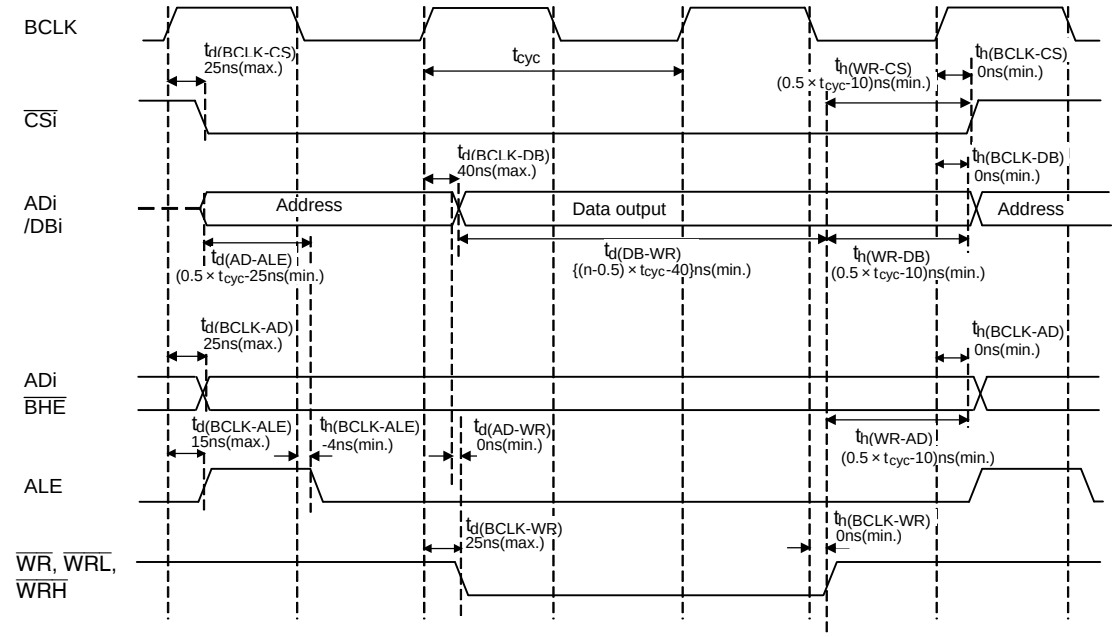
Memory Expansion Mode and Microprocessor Mode
(in 2 or 3 waits setting, and when accessing external area and using multiplexed bus)

$V_{CC1} = V_{CC2} = 5V$

Read timing



Write timing



n: 2 (when 2 waits)
3 (when 3 waits)

Measuring conditions

- $V_{CC1} = V_{CC2} = 5V$
- Input timing voltage: $V_{IL} = 0.8$ V, $V_{IH} = 2.0$ V
- Output timing voltage: $V_{OL} = 0.4$ V, $V_{OH} = 2.4$ V

Figure 5.17 Timing Diagram

$V_{CC1} = V_{CC2} = 3\ V$

Table 5.44 Electrical Characteristics (2)

R5F36506NFA, R5F36506NFB, R5F36506DFA, R5F36506DFB, R5F3650ENFA, R5F3650ENFB, R5F3650EDFA, R5F3650EDFB

$V_{CC1} = V_{CC2} = 2.7$ to 3.3 V, $V_{SS} = 0$ V at $T_{opr} = -20°C$ to 85°C/–40°C to 85°C, $f_{(BCLK)} = 32$ MHz unless otherwise specified.

Symbol	Parameter	Measuring Condition		Standard			Unit
				Min.	Typ.	Max.	
R_{fXCIN}	Feedback resistance XCIN				16		MΩ
I_{CC}	Power supply current In single-chip, mode, the output pin are open and other pins are V_{SS}	High-speed mode	$f_{(BCLK)}$ = 32 MHz XIN = 4 MHz (square wave), PLL multiplied by 8 125 kHz on-chip oscillator stopped		24.0		mA
			$f_{(BCLK)}$ = 32 MHz, A/D conversion XIN = 4 MHz (square wave), PLL multiplied by 8 125 kHz on-chip oscillator stopped		24.7		mA
			$f_{(BCLK)}$ = 20 MHz XIN = 20 MHz (square wave) 125 kHz on-chip oscillator stopped		16.0		mA
		40 MHz on-chip oscillator mode	Main clock stopped 40 MHz on-chip oscillator on, divide-by-4 ($f_{(BCLK)}$ = 10 MHz) 125 kHz on-chip oscillator stopped		17.0		mA
		125 kHz on-chip oscillator mode	Main clock stopped 40 MHz on-chip oscillator stopped 125 kHz on-chip oscillator on, no division FMR22 = 1 (slow read mode)		450.0		µA
		Low-power mode	$f_{(BCLK)}$ = 32 MHz In low-power mode FMR 22 = FMR23 = 1 On flash memory (1)		160.0		µA
			$f_{(BCLK)}$ = 32 MHz In low-power mode On RAM (1)		40.0		µA
		Wait mode	Main clock stopped 40 MHz on-chip oscillator stopped 125 kHz on-chip oscillator on Peripheral clock operating T_{opr} = 25°C		20.0		µA
			$f_{(BCLK)}$ = 32 MHz (oscillation capacity High) 40 MHz on-chip oscillator stopped 125 kHz on-chip oscillator stopped Peripheral clock operating T_{opr} = 25°C		8.0		µA
			$f_{(BCLK)}$ = 32 kHz (oscillation capacity Low) 40 MHz on-chip oscillator stopped 125 kHz on-chip oscillator stopped Peripheral clock operating T_{opr} = 25°C		4.0		µA
		Stop mode	Main clock stopped 40 MHz on-chip oscillator stopped 125 kHz on-chip oscillator stopped Peripheral clock stopped T_{opr} = 25°C		1.6		µA
		During flash memory program	$f_{(BCLK)}$ = 10 MHz, PM17 = 1 (one wait) V_{CC1} = 3.0 V		20.0		mA
		During flash memory erase	$f_{(BCLK)}$ = 10 MHz, PM17 = 1 (one wait) V_{CC1} = 3.0 V		30.0		mA

Note:
1. This indicates the memory in which the program to be executed exists.

$V_{CC1} = V_{CC2} = 3\ V$

Timing Requirements

($V_{CC1} = V_{CC2} = 3$ V, $V_{SS} = 0$ V, at $T_{opr} = -20°C$ to 85°C/-40°C to 85°C unless otherwise specified)

5.3.2.7 Multi-master I²C-bus

Table 5.59 Multi-master I²C-bus

Symbol	Parameter	Standard Clock Mode		Fast-mode		Unit
		Min.	Max.	Min.	Max.	
t_{BUF}	Bus free time	4.7		1.3		µs
$t_{HD;STA}$	Hold time in start condition	4.0		0.6		µs
t_{LOW}	Hold time in SCL clock 0 status	4.7		1.3		µs
t_R	SCL, SDA signals' rising time		1000	20 + 0.1 Cb	300	ns
$t_{HD;DAT}$	Data hold time	0		0	0.9	µs
t_{HIGH}	Hold time in SCL clock 1 status	4.0		0.6		µs
f_F	SCL, SDA signals' falling time		300	20 + 0.1 Cb	300	ns
$t_{su;DAT}$	Data setup time	250		100		ns
$t_{su;STA}$	Setup time in restart condition	4.7		0.6		µs
$t_{su;STO}$	Stop condition setup time	4.0		0.6		µs

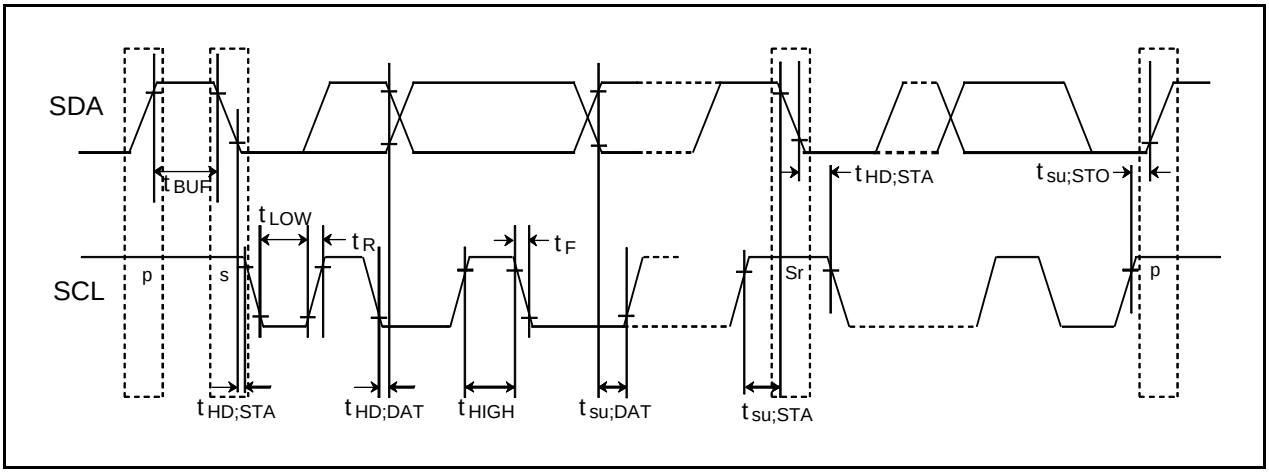
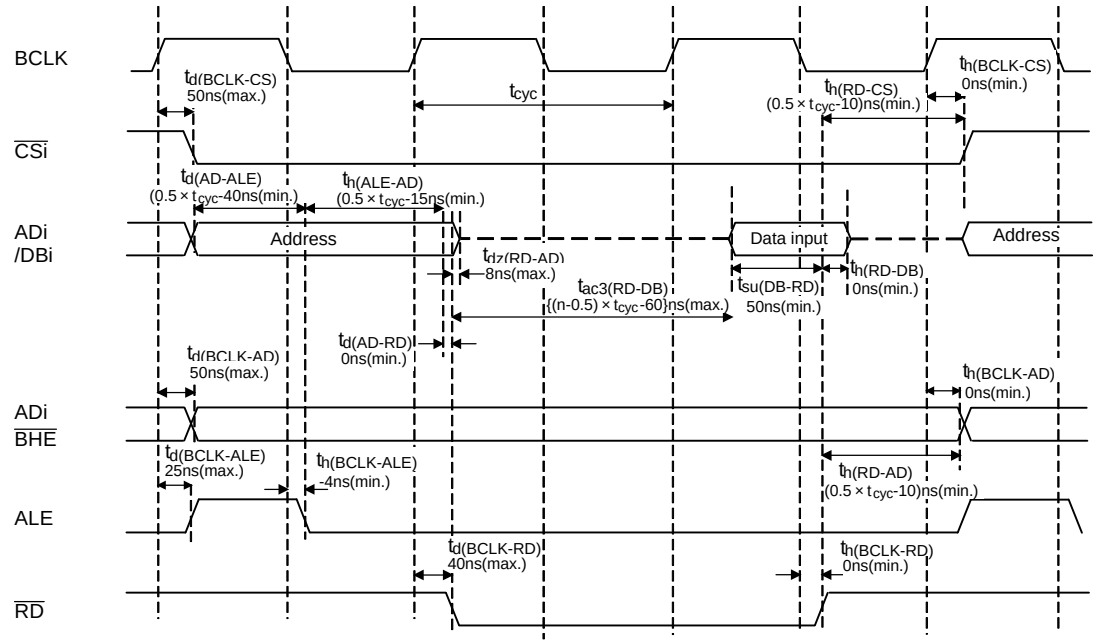


Figure 5.27 Multi-master I²C-bus

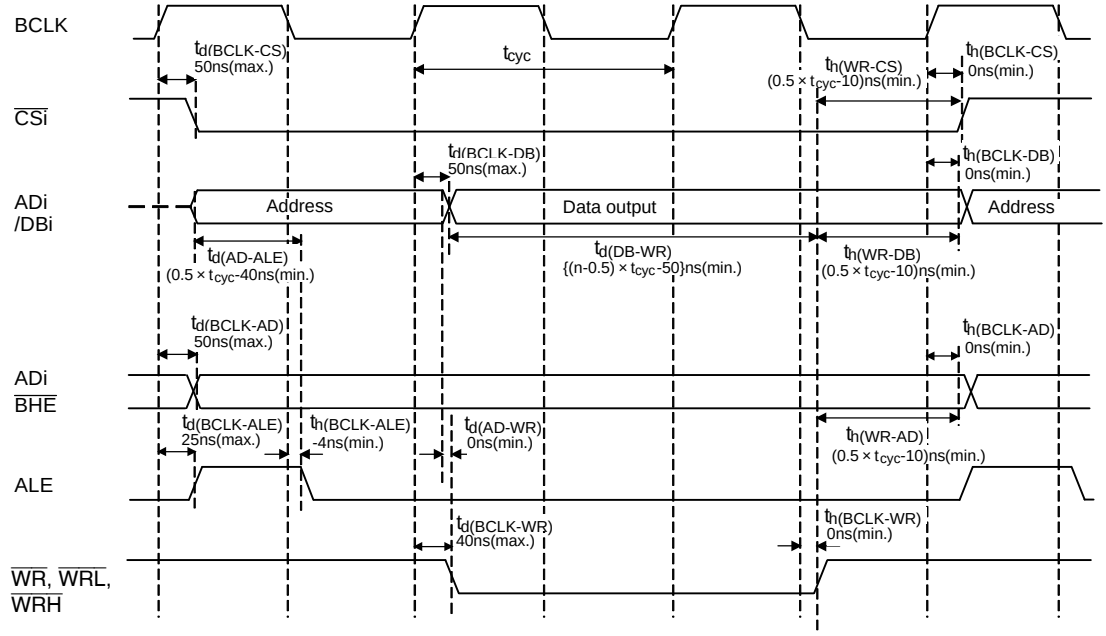
$V_{CC1} = V_{CC2} = 3V$

Memory Expansion Mode and Microprocessor Mode
(in 2 or 3 waits setting, and when accessing external area and using multiplexed bus)

Read timing



Write timing



$$t_{cyc} = \frac{1}{f_{(BCLK)}}$$

Measuring conditions

- $V_{CC1} = V_{CC2} = 3V$
- Input timing voltage: $V_{IL} = 0.6$ V, $V_{IH} = 2.4$ V
- Output timing voltage: $V_{OL} = 1.5$ V, $V_{OH} = 1.5$ V

n: 2 (when 2 waits)
3 (when 3 waits)

Figure 5.32 Timing Diagram

$V_{CC1} = V_{CC2} = 3\ V$

Switching Characteristics

($V_{CC1} = V_{CC2} = 3$ V, $V_{SS} = 0$ V, at $T_{opr} = -20°C$ to 85°C/-40°C to 85°C unless otherwise specified)

5.3.4.4 In Wait State Setting 2φ + 3φ, 2φ + 4φ, 3φ + 4φ, and 4φ + 5φ, and When Accessing External Area

Table 5.64 Memory Expansion and Microprocessor Modes (in Wait State Setting 2φ + 3φ, 2φ + 4φ, 3φ + 4φ, and 4φ + 5φ, and When Accessing External Area)

Symbol	Parameter	Measuring Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address output delay time	See Figure 5.29		30	ns
$t_{h(BCLK-AD)}$	Address output hold time (in relation to BCLK)		0		ns
$t_{h(RD-AD)}$	Address output hold time (in relation to RD)		0		ns
$t_{h(WR-AD)}$	Address output hold time (in relation to WR)		(Note 2)		ns
$t_{d(BCLK-CS)}$	Chip select output delay time			30	ns
$t_{h(BCLK-CS)}$	Chip select output hold time (in relation to BCLK)		0		ns
$t_{d(BCLK-ALE)}$	ALE signal output delay time			25	ns
$t_{h(BCLK-ALE)}$	ALE signal output hold time		-4		ns
$t_{d(BCLK-RD)}$	RD signal output delay time			30	ns
$t_{h(BCLK-RD)}$	RD signal output hold time		0		ns
$t_{d(BCLK-WR)}$	WR signal output delay time			30	ns
$t_{h(BCLK-WR)}$	WR signal output hold time		0		ns
$t_{d(BCLK-DB)}$	Data output delay time (in relation to BCLK)			40	ns
$t_{h(BCLK-DB)}$	Data output hold time (in relation to BCLK) (3)		0		ns
$t_{d(DB-WR)}$	Data output delay time (in relation to WR)		(Note 1)		ns
$t_{h(WR-DB)}$	Data output hold time (in relation to WR) (3)		(Note 2)		ns

Notes:

1. Calculated according to the BCLK frequency as follows:

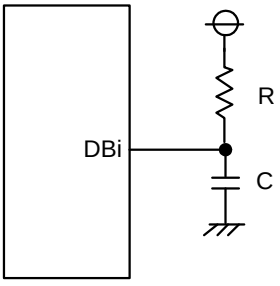
$$\frac{(n-0.5)\times 10^9}{f_{(BCLK)}} - 40[ns]$$

n is 3 for 2φ + 3φ, 4 for 2φ + 4φ, 4 for 3φ + 4φ, and 5 for 4φ + 5φ.

2. Calculated according to the BCLK frequency as follows:

$$\frac{0.5\times 10^9}{f_{(BCLK)}} - 10[ns]$$

3. This standard value shows the timing when the output is off, and does not show hold time of data bus.
Hold time of data bus varies with capacitor volume and pull-up (pull-down) resistance value.
Hold time of data bus is expressed in
$t = -CR \times \ln(1 - V_{OL}/V_{CC2})$
by a circuit of the right figure.
For example, when $V_{OL} = 0.2V_{CC2}$, C = 30 pF, R = 1 kΩ, hold time of output low level is
$t = -30\ pF \times 1\ k\Omega \times \ln(1 - 0.2V_{CC2}/V_{CC2})$
= 6.7 ns.



$V_{CC1} = V_{CC2} = 3\ V$

Switching Characteristics

($V_{CC1} = V_{CC2} = 3$ V, $V_{SS} = 0$ V, at $T_{opr} = -20°C$ to 85°C/-40°C to 85°C unless otherwise specified)

5.3.4.5 In Wait State Setting 2φ + 3φ, 2φ + 4φ, 3φ + 4φ, and 4φ + 5φ, and Inserting 1 to 3 Recovery Cycles and Accessing External Area

Table 5.65 Memory Expansion Mode and Microprocessor Mode (in Wait State Setting 2φ + 3φ, 2φ + 4φ, 3φ + 4φ, and 4φ + 5φ, and Inserting 1 to 3 Recovery Cycles and Accessing External Area)

Symbol	Parameter	Measuring Condition	Standard		Unit
			Min.	Max.	
$t_{d(BCLK-AD)}$	Address output delay time	See Figure 5.29		30	ns
$t_{h(BCLK-AD)}$	Address output hold time (in relation to BCLK)		0		ns
$t_{h(RD-AD)}$	Address output hold time (in relation to RD)		(Note 4)		ns
$t_{h(WR-AD)}$	Address output hold time (in relation to WR)		(Note 2)		ns
$t_{d(BCLK-CS)}$	Chip select output delay time			30	ns
$t_{h(BCLK-CS)}$	Chip select output hold time (in relation to BCLK)		0		ns
$t_{d(BCLK-ALE)}$	ALE signal output delay time			25	ns
$t_{h(BCLK-ALE)}$	ALE signal output hold time		-4		ns
$t_{d(BCLK-RD)}$	RD signal output delay time			30	ns
$t_{h(BCLK-RD)}$	RD signal output hold time		0		ns
$t_{d(BCLK-WR)}$	WR signal output delay time			30	ns
$t_{h(BCLK-WR)}$	WR signal output hold time		0		ns
$t_{d(BCLK-DB)}$	Data output delay time (in relation to BCLK)			40	ns
$t_{h(BCLK-DB)}$	Data output hold time (in relation to BCLK) (3)		0		ns
$t_{d(DB-WR)}$	Data output delay time (in relation to WR)		(Note 1)		ns
$t_{h(WR-DB)}$	Data output hold time (in relation to WR) (3)		(Note 2)		ns

Notes:

1. Calculated according to the BCLK frequency as follows:

$$\frac{n \times 10^9}{f_{(BCLK)}} - 40[ns]$$

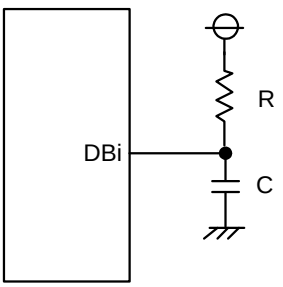
n is 3 for 2φ + 3φ, 4 for 2φ + 4φ, 4 for 3φ + 4φ, and 5 for 4φ + 5φ.

2. Calculated according to the BCLK frequency as follows:

$$\frac{m \times 10^9}{f_{(BCLK)}} - 10[ns]$$

m is 1 when 1 recovery cycle is inserted, 2 when 2 recovery cycles are inserted, and 3 when 3 recovery cycles are inserted.

3. This standard value shows the timing when the output is off, and does not show hold time of data bus.
Hold time of data bus varies with capacitor volume and pull-up (pull-down) resistance value.
Hold time of data bus is expressed in
$t = -CR \times \ln(1 - V_{OL}/V_{CC2})$
by a circuit of the right figure.
For example, when $V_{OL} = 0.2V_{CC2}$, C = 30 pF, R = 1 kΩ, hold time of output low level is
$t = -30\ pF \times 1\ k\Omega \times \ln(1 - 0.2V_{CC2}/V_{CC2})$
= 6.7 ns.



4. Calculated according to the BCLK frequency as follows:

$$\frac{m \times 10^9}{f_{(BCLK)}} + 0[ns]$$

m is 1 when 1 recovery cycle is inserted, 2 when 2 recovery cycles are inserted, and 3 when 3 recovery cycles are inserted.